

Appl. No. 10/650,602

Amdt. dated 06/20/2006

Reply to Office action of 05/26/2006

Amendments to the Specification

Please replace the fourth paragraph on page 6 with the following amended paragraph:

Next, upper magnetic shield layer 12 is deposited on CPP GMR stack 11 followed by the deposition (on upper magnetic shield 12) of upper conductive layer 32. Another key feature of the invention is that layer 32 must have an electrical resistance that is between about 0.2[5] and 0.1[10] times the in-plane resistance of layer 12.